

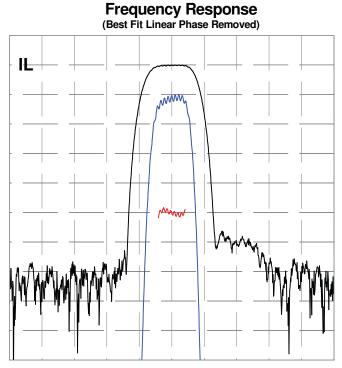
## **Specifications**

Parameter	Symbol	Min	Typical	Max	Unit
Center Frequency	Fo		700		MHz
Bandwidth	В		1.4		MHz
–3 dB Bandwidth	B <sub>3</sub>	2	2.1		MHz
-40 dB Bandwidth	B <sub>40</sub>		3.7	3.8	MHz
Delay	To	2.96	2.998	3.02	µsec
Insertion Loss	IL		20.5	22.5	dB
Amplitude Ripple			0.5	1	dB <sub>P-P</sub>
Phase Ripple			4.1	8	deg <sub>P-P</sub>
Rejection		39	40		dB
Spurious for $ t - T_0  > .9T_0$			-38	-35	dB
Substrate Material	30YX-Q				

### Notes

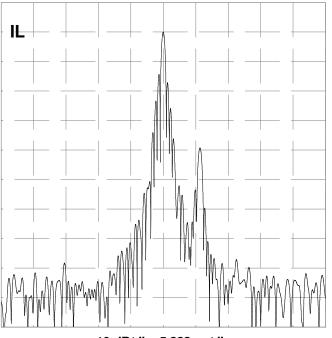
- 1. Center Frequency (F<sub>0</sub>) and Bandwidth (B) are defined, not measured.
- 2. Insertion Loss is the minimum loss for  $|f F_0| < .5B$
- 3. Ripple spec applies to the  $|f F_0| < .4B$ , and is doubled for  $.4B < |f F_0| < .5B$
- 4. Rejection spec applies to  $(B_{40} \text{ Spec} B/2) < |f F_0| < F_0/2$
- 5. Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts dF<sub>0</sub> =  $-x^*$  F<sub>0</sub>, dT<sub>0</sub> =  $x^*$  T<sub>0</sub>, where  $x = 3E-8^*$  (temperature -22 °C)<sup>2</sup>

## **Typical Performance**



10 dB/div, 1 dB/div, 10 deg/div, 1.500 MHz/div

Impulse Response FFT(Frequency Response\*Cos(0.5\*PI\*MIN(1,MAX(0,|f-F0|\*2.0/B-1.0)))^2)

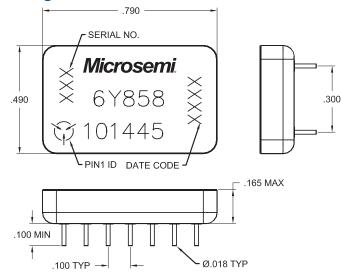


10 dB/div, 5.333 us/div

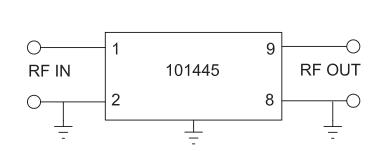


# 101445C FB700-1.4 700 MHz Bandpass Filter 1.4 MHz Bandwidth

## **Package Outline**



## Matching





#### Microsemi Corporate Headquarters One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Fax: +1 (949) 215-4996 Email: sales.support@microsemi.com www.microsemi.com

©2017 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions, security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, California and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information provided in this document or to any products and services at any time without notice.

MSCC-0347-DS-01157-2.00-0717